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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/777,189	02/13/2004	Shigetoshi Wakayama	042107 8258		
38834	7590 05/16/2006	EXAMINER			
	N, HATTORI, DANIEL	PHAM, HOAI V			
SUITE 700	CTICUT AVENUE, NW	ART UNIT	PAPER NUMBER		
WASHINGTON, DC 20036			2814		
			DATE MAILED: 05/16/2000	DATE MAILED: 05/16/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application	n No.	Applicant(s)				
Office Action Summary		10/777,189	)	WAKAYAMA ET AL.				
		Examiner		Art Unit				
		Hoai v. Pha		2814				
Period fo	The MAILING DATE of this communication ap or Reply	pears on the	cover sheet with the	correspondence address	•-			
THE - Exte after - If the - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPL MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. Period for reply specified above is less than thirty (30) days, a replay to period for reply is specified above, the maximum statutory period preserved by the Office later than three months after the mailing and patent term adjustment. See 37 CFR 1.704(b).	136(a). In no even bly within the statut will apply and will e, cause the applic	t, however, may a reply be til ory minimum of thirty (30) day expire SIX (6) MONTHS from ation to become ABANDONE	mely filed ys will be considered timely. n the mailing date of this communic ED (35 U.S.C. § 133).	cation.			
Status								
1) 🛛	Responsive to communication(s) filed on 13 F	ebruary 2004	4.					
·	a) ☑ This action is <b>FINAL</b> . 2b) ☑ This action is non-final.							
3)	<u>, —</u>							
·	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.							
Disposit	ion of Claims							
5)□ 6)⊠ 7)□	Claim(s) 1-15 is/are pending in the application 4a) Of the above claim(s) 5 and 7-15 is/are with Claim(s) is/are allowed.  Claim(s) 1-4 and 6 is/are rejected.  Claim(s) is/are objected to.  Claim(s) are subject to restriction and/o	thdrawn from						
Applicati	ion Papers							
9)	The specification is objected to by the Examine	er.						
10)	The drawing(s) filed on is/are: a) acc	cepted or b)	objected to by the	Examiner.				
	Applicant may not request that any objection to the	e drawing(s) be	held in abeyance. Se	e 37 CFR 1.85(a).				
—	Replacement drawing sheet(s) including the correct	•	• • •	•	. ,			
11)	The oath or declaration is objected to by the E.	xaminer. Not	e the attached Office	Action or form PTO-15	2.			
Priority (	ınder 35 U.S.C. § 119							
a)l	Acknowledgment is made of a claim for foreign  All b) Some * c) None of:  1. Certified copies of the priority document  2. Certified copies of the priority document  3. Copies of the certified copies of the priority document  application from the International Burea	its have been its have been prity documer au (PCT Rule	received. received in Applicat its have been receiv 17.2(a)).	ion No ed in this National Stage	<b>:</b>			
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Attachmen			🗀					
	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948)		4) Interview Summary Paper No(s)/Mail D					
3) 🔲 Inform	mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date	•		Patent Application (PTO-152)				

### **DETAILED ACTION**

#### Election/Restrictions

- Applicant's election without traverse species of figure 3 in the reply filed on
   March 03, 2006 is acknowledged.
- 2. Claims 7-15 are not under consideration since they are not read on species of figure 3. Claims 7-15 specifically belong to species of figure 9.

# Claim Rejections - 35 USC § 102

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 4. Claims 1-4, 6 are rejected under 35 U.S.C. 102(b) as being anticipated by Umematsu et al. [U.S. Pat. 6,399,897] previously applied.

With respect to claim 1, Umematsu et al. (fig. 5B, col. 5) discloses a semiconductor device, comprising:

semiconductor substrate (12) (see col. 3, lines 8-9); and

a multilayer interconnection structure formed on said substrate, said multilayer interconnection structure comprising:

a first guard ring (58a) extending continuously in said multilayer interconnection structure along periphery (50) of said semiconductor substrate; and

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a second guard ring (58a) extending continuously in said multilayer interconnection structure along said periphery so as to be encircled by said first guard ring, said second guard ring encircling an interconnection pattern inside said multilayer interconnection structure;

said first and second guard rings (58a) being connected with each other mechanically and continuously by a bridging conductor pattern (56a) extending continuously in a band form along a region including said first and second guard rings, when viewed in the direction perpendicular to said semiconductor substrate.

With respect to claim 2, Umematsu et al. discloses that wherein said bridging conductor pattern (56a) does not have any of a gap or an opening (fig. 5B).

With respect to claim 3, Umematsu et al. discloses that wherein said bridging conductor pattern (56a) is provided at plural different positions having different heights as measured from a surface of said semiconductor substrate (fig. 5B).

With respect to claim 4, Umematsu et al. discloses that wherein said bridging conductor pattern (56a) is formed in one or more interlayer insulation films (49a-49i) in said multilayer interconnection structure.

With respect to claim 6, Umematsu et al. discloses that wherein said multilayer interconnection structure has a layered structure in which a plurality of interlayer

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insulation films (49a-49i) each including an interconnection layer corresponding thereto are stacked, and wherein an interconnection layer formed in one interlayer insulation film of said plural interlayer insulation films is connected to an underlying interconnection layer by a via-plug (58, 58a), each of said first and second guard rings having a layered structure identical to that of said multilayer interconnection structure, said bridging conductor pattern being formed at a height identical to that of the interconnection layer in said interlayer insulation film in which said bridging conductor pattern is formed (fee fig. 5b).

# Response to Arguments

5. Applicant's arguments filed 11/18/2005 have been fully considered but they are not persuasive.

Applicant argues that Umematsu et al. does not disclose "a first and second guard rings (58a) being connected with each other mechanically and continuously by a bridging conductor pattern (56a) extending continuously in a band form along a region including said first and second guard rings, when viewed in the direction perpendicular to said semiconductor substrate".

Applicant's argument is not persuasive because Umematsu et al. clearly disclose a first and second guard rings (58a) being connected with each other mechanically and continuously by a bridging conductor pattern (56a) extending continuously in a band form along a region including said first and second guard rings, when viewed (cross

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sectional view) in the direction perpendicular to said semiconductor substrate (see fig. 5B).

## Conclusion

- 6. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).
- 7. A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.
- 8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hoai v. Pham whose telephone number is 571-272-1715. The examiner can normally be reached on M-F.
- 9. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael M. Fahmy can be reached on 571-272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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10. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

HOAI PHAM
PRIMARY EXAMINER